

# Author Index for Papers in Volume 26

Pages are numbered consecutively through the volume: 1-132, January; 133-274, March; 275-396, May; 397-524, July; 525-644, September; and 645-790, November.

**Abdou, Ikram E.** and Kwan Y. Wong

667 *Analysis of Linear Interpolation Schemes for Bi-Level Image Applications*

**Acosta, R. E.**

286 see Ho, C. W.

**Acosta, R. E.**

136 see von Gutfeld, R. J.

**Agnew, P. W.** and A. S. Kellerman

401 *Microprocessor Implementation of Mainframe Processors by Means of Architecture Partitioning*

**Alvarez, D. C.**

217 see Bräuchle, Chr.

**Anastassiou, Dimitris** and Keith S. Pennington

687 *Digital Halftoning of Images*

**Asselta, John A.**

297 see Bonner, Roy F.

**Babuka, R.**, G. J. Saxenmeyer, Jr., and L. K. Schultz

318 *Development of Interconnection Technology for Large-Scale Integrated Circuits*

**Bahnsen, Ralph J.**

106 see Smith, Gordon L.

**Bajorek, C. H.**

286 see Ho, C. W.

**Balanson, Richard D.**

186 see Tam, Andrew C.

**Barbour, D. R.**

30 see Blodgett, A. J.

**Barnes, E. R.**

759 *An Algorithm for Separating Patterns by Ellipsoids*

**Bendz, D. J.**, R. W. Gedney, and J. Rasile

278 *Cost/Performance Single-Chip Module*

**Bergendahl, A. S.**, S. F. Bergeron, and D. L. Harmon

580 *Optimization of Plasma Processing for Silicon-Gate FET Manufacturing Applications*

**Bergeron, S. F.**

580 see Bergendahl, A. S.

**Bernstein, Ralph**

715 see Dave, Jitendra V.

**Bjorklund, G. C.**

217 see Bräuchle, Chr.

**Blodgett, A. J.** and D. R. Barbour

30 *Thermal Conduction Module: A High-Performance Multi-layer Ceramic Package*

**Bohlen, H.**, J. Greschner, J. Keyser, W. Kulcke, and P. Nehmiz

568 *Electron-Beam Proximity Printing—A New High-Speed Lithography Method for Submicron Structures*

**Bonner, Roy F.**, John A. Asselta, and Frank W. Haining

297 *Advanced Printed-Circuit Board Design for High-Performance Computer Applications*

**Bossen, D. C.** and M. Y. Hsiao

67 *Model for Transient and Permanent Error-Detection and Fault-Isolation Coverage*

**Bräuchle, Chr.**, Urs P. Wild, D. M. Burland, G. C. Bjorklund, and D. C. Alvarez

217 *A New Class of Materials for Holography in the Infrared*

**Brickman, Norman F.** and Walter S. Rosenbaum

681 *Word Autocorrelation Redundancy Match (WARM) Technology*

**Brown, M. D.**

440 see Dix, G. L.

**Bupp, J. R.**, L. N. Chellis, R. E. Ruane, and J. P. Wiley

306 *High-Density Board Fabrication Techniques*

**Burgess, Robert M.**, Kathleen B. Koens, and Emil M. Pignetti, Jr.

605 *Semiconductor Final Test Logistics and Product Dispositioning Systems*

**Burland, D. M.**

217 see Bräuchle, Chr.

**Campbell, John E.** and Joseph Tahmoush

454 *Design Considerations for a VLSI Microprocessor*

**Carre, H.**, R. H. Doxtator, and M. C. Duffy

528 *Semiconductor Manufacturing Technology at IBM*

**Casey, R. G.**, T. D. Friedman, and K. Y. Wong

657 *Automatic Scaling of Digital Print Fonts*

**Casey, R. G.**

647 see Wong, Kwan Y.

**Castrucci, P. P.**

532 see Stapper, C. H.

**Chance, D. A.**

286 see Ho, C. W.

**Chellis, L. N.**

306 see Bupp, J. R.

**Cheng, David D.**

100 see Hitchcock, Robert B., Sr.

**Chiang, K.**

160 see Levenson, M. D.

**Chu, R. C.**, U. P. Hwang, and R. E. Simons

45 *Conduction Cooling for an LSI Package: A One-Dimensional Approach*

**Chu, Wei-Kan**

171 see Kiang, Ying C.

**Chuang, T. J.**

145 *Laser-Enhanced Chemical Etching of Solid Surfaces*

**Collins, George G.** and Cary W. Halsted

596 *Process Control of the Chlorobenzene Single-Step Liftoff Process with a Diazo-Type Resist*

**Combronde, J.**

546 see Murgai, A.

**Cooley, James W.**

424 *Rectangular Transforms for Digital Convolution on the Research Signal Processor*

**Correale, Anthony**

446 *Physical Design of a Custom 16-Bit Microprocessor*

**Crow, J. D.**

177 see Dewey, A. G.

**Curtis, R. T.**

613 see Melan, E. H.

**Danielsson, Per-Erik**

698 *An Improved Segmentation and Coding Algorithm for Binary and Nonbinary Images*

**Dave, Jitendra V.**, Ralph Bernstein, and Harwood G. Kolsky

715 *Importance of Higher-Order Components to Multispectral Classification*

**Davidson, E. E.**

349 *Electrical Design of a High Speed Computer Package*

- Davies, Ken** and Fred Ris  
431 *Real-Time Signal Processor Software Support*
- Dewey, A. G.** and J. D. Crow  
177 *The Application of GaAlAs Lasers to High-Resolution Liquid-Crystal Projection Displays*
- Dickson, LeRoy D.**, Glenn T. Sincerbox, and Albert D. Wolfheimer  
228 *Holography in the IBM 3687 Supermarket Scanner*
- Dix, G. L.** and M. D. Brown  
440 *Common Chip for Use in Disk and Diskette Controllers*
- Doxlator, R. H.**  
528 see Carre, H.
- Duffy, M. C.**  
528 see Carre, H.
- Farrell, Edward J.**  
746 *Backscatter and Attenuation Imaging from Ultrasonic Scanning in Medicine*
- Felix, J. C.**  
546 see Murgai, A.
- Forsberg, Richard A.**  
475 see Tran, Arnold S.
- Franaszek, P. A.**  
506 *Construction of Bounded Delay Codes for Discrete Noiseless Channels*
- Frasch, P.** and K. H. Saremski  
561 *Feature Size Control in IC Manufacturing*
- Fried, L. J.**, J. Havas, J. S. Lechaton, J. S. Logan, G. Paal, and P. A. Totta  
362 *A VLSI Bipolar Metallization Design with Three-Level Wiring and Area Array Solder Connections*
- Friedman, T. D.**  
657 see Casey, R. G.
- Friedrich, J.**  
198 see Gutiérrez, A. R.
- Gedney, R. W.**  
278 see Bendz, D. J.
- Getten, J. R.** and R. C. Senger  
379 *Immersion Wave Soldering Process*
- Greschner, J.**  
568 see Bohlen, H.
- Griscom, Robert**  
22 see Reilly, John
- Gustafson, R. N.** and F. J. Sparacio  
12 *IBM 3081 Processor Unit: Design Considerations and Design Process*
- Gutiérrez, A. R.**, J. Friedrich, D. Haarer, and H. Wolfrum  
198 *Multiple Photochemical Hole Burning in Organic Glasses and Polymers: Spectroscopy and Storage Aspects*
- Haarer, D.**  
198 see Gutiérrez, A. R.
- Haining, Frank W.**  
297 see Bonner, Roy F.
- Halliwell, Harry**  
106 see Smith, Gordon L.
- Halsted, Cary W.**  
596 see Collins, George G.
- Halverson, R. M.**, M. W. MacIntyre, and W. T. Motsiff  
590 *The Mechanism of Single-Step Liftoff with Chlorobenzene in a Diazo-Type Resist*
- Harmon, D. L.**  
580 see Bergendahl, A. S.
- Havas, J.**  
362 see Fried, L. J.
- Heller, W. R.**  
328 see Koch, J. H. III
- Hitchcock, Robert B., Sr.**, Gordon L. Smith, and David D. Cheng  
100 *Timing Analysis of Computer Hardware*
- Ho, C. W.**, D. A. Chance, C. H. Bajorek, and R. E. Acosta  
286 *The Thin-Film Module as a High-Performance Semiconductor Package*
- Ho, J. K.**  
613 see Melan, E. H.
- Hodgson, R. T.**, André B. Minn, and James D. Rockrohr  
235 *Laser-Induced Arcing in Cathode Ray Tubes*
- Hofmann, J.** and H. Schmutz  
242 *Performance Analysis of Suspend Locks in Operating Systems*
- Howard, Robert T.**  
372 *Optimization of Indium-Lead Alloys for Controlled Collapse Chip Connection Application*
- Hsiao, M. Y.**  
67 see Bossen, D. C.
- Hwang, U. P.**  
45 see Chu, R. C.
- Jain, K.**, C. G. Willson, and B. J. Lin  
151 *Ultrafast High-Resolution Contact Lithography with Excimer Lasers*
- Jimenez, Javier** and Jose L. Navalon  
724 *Some Experiments in Image Vectorization*
- Kammerer, H. C.**  
55 see Oktay, S.
- Kellerman, A. S.**  
401 see Agnew, P. W.
- Keyser, J.**  
568 see Bohlen, H.
- Kiang, Ying C.**, J. Randal Moulic, Wei-Kan Chu, and Andrew C. Yen  
171 *Modification of Semiconductor Device Characteristics by Lasers*
- Koch, J. H. III**, W. F. Mikhail, and W. R. Heller  
328 *Influence on LSI Package Wireability of Via Availability and Wiring Track Accessibility*
- Koens, J. G.**  
613 see Melan, E. H.
- Koens, Kathleen B.**  
605 see Burgess, Robert M.
- Kolsky, Harwood G.**  
715 see Dave, Jitendra V.
- Kriz, Thomas A.**  
708 *Reduced Data Re-Order Complexity Properties of Polynomial Transform 2D Convolution and Fourier Transform Methods*
- Kulcke, W.**  
568 see Bohlen, H.
- Lechaton, J. S.**  
362 see Fried, L. J.
- Lee, Jack C.**  
475 see Tran, Arnold S.
- Lee, L. P.**  
464 see Mathews, K. F.
- Levenson, M. D.** and K. Chiang  
160 *Image Projection with Nonlinear Optics*

- Lin, B. J.**  
151 see Jain, K.
- Logan, J. S.**  
362 see Fried, L. J.
- MacIntyre, M. W.**  
590 see Halverson, R. M.
- Maeder, R. A.**  
532 see Stapper, C. H.
- Mathews, K. F. and L. P. Lee**  
464 *Bipolar Chip Design for a VLSI Microprocessor*
- McCabe, J. F. and A. Z. Muszynski**  
485 *A Bipolar VLSI Custom Macro Physical Design Verification Strategy*
- Melan, E. H., R. T. Curtis, J. K. Ho, J. G. Koens, and G. A. Snyder**  
613 *Quality and Reliability Assurance Systems in IBM Semiconductor Manufacturing*
- Mescia, N. C. and C. D. Woods**  
497 *Plant Automation in a Structured Distributed System Environment*
- Mikhail, W. F.**  
328 see Koch, J. H. III
- Minn, André B.**  
235 see Hodgson, R. T.
- Mintzer, Fred and Abraham Peled**  
413 *A Microprocessor for Signal Processing, the RSP*
- Monachino, Michael**  
89 *Design Verification System for Large-Scale LSI Designs*
- Montoto, Luis**  
735 *Digital Multi-Image Analysis: Application to the Quantification of Rock Microfractography*
- Motsiff, W. T.**  
590 see Halverson, R. M.
- Moulic, J. Randal**  
171 see Kiang, Ying C.
- Murgai, A., W. J. Patrick, J. Combronde, and J. C. Felix**  
546 *Oxygen Incorporation and Precipitation in Czochralski-Grown Silicon*
- Muszynski, A. Z.**  
485 see McCabe, J. F.
- Nasser, Robert**  
22 see Reilly, John
- Navalon, Jose L.**  
724 see Jimenez, Javier
- Nehmiz, P.**  
568 see Bohlen, H.
- Oktay, S. and H. C. Kammerer**  
55 *A Conduction-Cooled Module for High-Performance LSI Devices*
- Paal, G.**  
362 see Fried, L. J.
- Patrick, W. J.**  
546 see Murgai, A.
- Peled, Abraham**  
413 see Mintzer, Fred
- Pennington, Keith S.**  
687 see Anastassiou, Dimitris
- Pignetti, Emil M., Jr.**  
605 see Burgess, Robert M.
- Pittler, M. S., D. M. Powers, and D. L. Schnabel**  
2 *System Development and Technology Aspects of the IBM 3081 Processor Complex*
- Powers, D. M.**  
2 see Pittler, M. S.
- Rabolt, J. F., R. Santo, N. E. Schlotter, and J. D. Swalen**  
209 *Integrated Optics and Raman Scattering: Molecular Orientation in Thin Polymer Films and Langmuir-Blodgett Monolayers*
- Rasile, J.**  
278 see Bendz, D. J.
- Reilly, John, Arthur Sutton, Robert Nasser, and Robert Griscom**  
22 *Processor Controller for the IBM 3081*
- Ris, Fred**  
431 see Davies, Ken
- Rockrohr, James D.**  
235 see Hodgson, R. T.
- Romankiw, L. T.**  
136 see von Gutfeld, R. J.
- Rosenbaum, Walter S.**  
681 see Brickman, Norman F.
- Rottmann, H. R.**  
553 *Metrology in Mask Manufacturing*
- Rowe, W. E.**  
532 see Stapper, C. H.
- Ruane, R. E.**  
306 see Bupp, J. R.
- Santo, R.**  
209 see Rabolt, J. F.
- Saremski, K. H.**  
561 see Frasc, P.
- Saxenmeyer, G. J., Jr.**  
318 see Babuka, R.
- Schlotter, N. E.**  
209 see Rabolt, J. F.
- Schmutz, H.**  
242 see Hofmann, J.
- Schnabel, D. L.**  
2 see Pittler, M. S.
- Schultz, L. K.**  
318 see Babuka, R.
- Senger, R. C.**  
379 see Getten, J. R.
- Seraphim, Donald P.**  
37 *A New Set of Printed-Circuit Technologies for the IBM 3081 Processor Unit*
- Shedler, Gerald S. and Jonathan Southard**  
625 *Regenerative Simulation of Networks of Queues with General Service Times: Passage Through Subnetworks*
- Simons, R. E.**  
45 see Chu, R. C.
- Sincerbox, Glenn T.**  
228 see Dickson, LeRoy D.
- Smith, Gordon L., Ralph J. Bahnsen, and Harry Halliwell**  
106 *Boolean Comparison of Hardware and Flowcharts*
- Smith, Gordon L.**  
100 see Hitchcock, Robert B., Sr.
- Snyder, G. A.**  
613 see Melan, E. H.
- Southard, Jonathan**  
625 see Shedler, Gerald S.

- Sparacio, F. J.**  
12 see Gustafson, R. N.
- Stapper, C. H.,** P. P. Castrucci, R. A. Maeder, W. E. Rowe, and R. A. Verhelst  
532 *Evolution and Accomplishments of VLSI Yield Management at IBM*
- Sutton, Arthur**  
22 see Reilly, John
- Swalen, J. D.**  
209 see Rabolt, J. F.
- Swann, Robert L.**  
78 see Tendolkar, Nandakumar N.
- Tahmoush, Joseph**  
454 see Campbell, John E.
- Tam, Andrew C.** and Richard D. Balanson  
186 *Lasers in Electrophotography*
- Tappert, C. C.**  
765 *Cursive Script Recognition by Elastic Matching*
- Tendolkar, Nandakumar N.** and Robert L. Swann  
78 *Automated Diagnostic Methodology for the IBM 3081 Processor Complex*
- Totta, P. A.**  
362 see Fried, L. J.
- Tran, Arnold S.,** Richard A. Forsberg, and Jack C. Lee  
475 *A VLSI Design Verification Strategy*
- Verhelst, R. A.**  
532 see Stapper, C. H.
- Vilkelis, W. V.**  
342 *Lead Reduction Among Combinatorial Logic Circuits*
- von Gutfeld, R. J.,** R. E. Acosta, and L. T. Romankiw  
136 *Laser-Enhanced Plating and Etching: Mechanisms and Applications*
- Wahl, F. M.**  
647 see Wong, K. Y.
- Wild, Urs P.**  
217 see Bräuchle, Chr.
- Wiley, J. P.**  
306 see Bupp, J. R.
- Willson, C. G.**  
151 see Jain, K.
- Wolfheimer, Albert D.**  
228 see Dickson, LeRoy D.
- Wolfrum, H.**  
198 see Gutiérrez, A. R.
- Wong, K. Y.,** R. G. Casey, and F. M. Wahl  
647 *Document Analysis System*
- Wong, K. Y.**  
657 see Casey, R. G.
- Wong, Kwan Y.**  
667 see Abdou, Ikram E.
- Woods, C. D.**  
497 see Mescia, N. C.
- Yen, Andrew C.**  
171 see Kiang, Ying C.